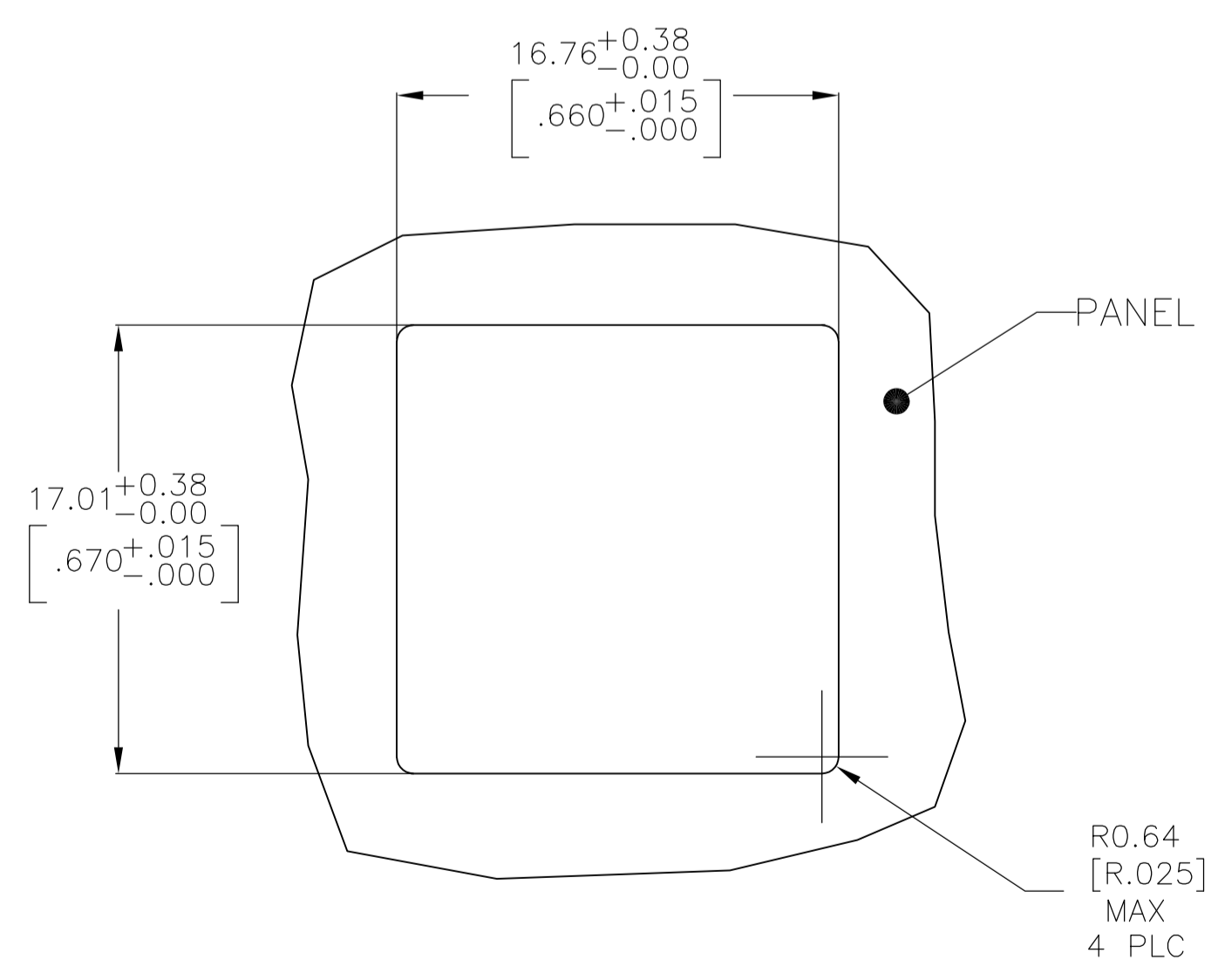
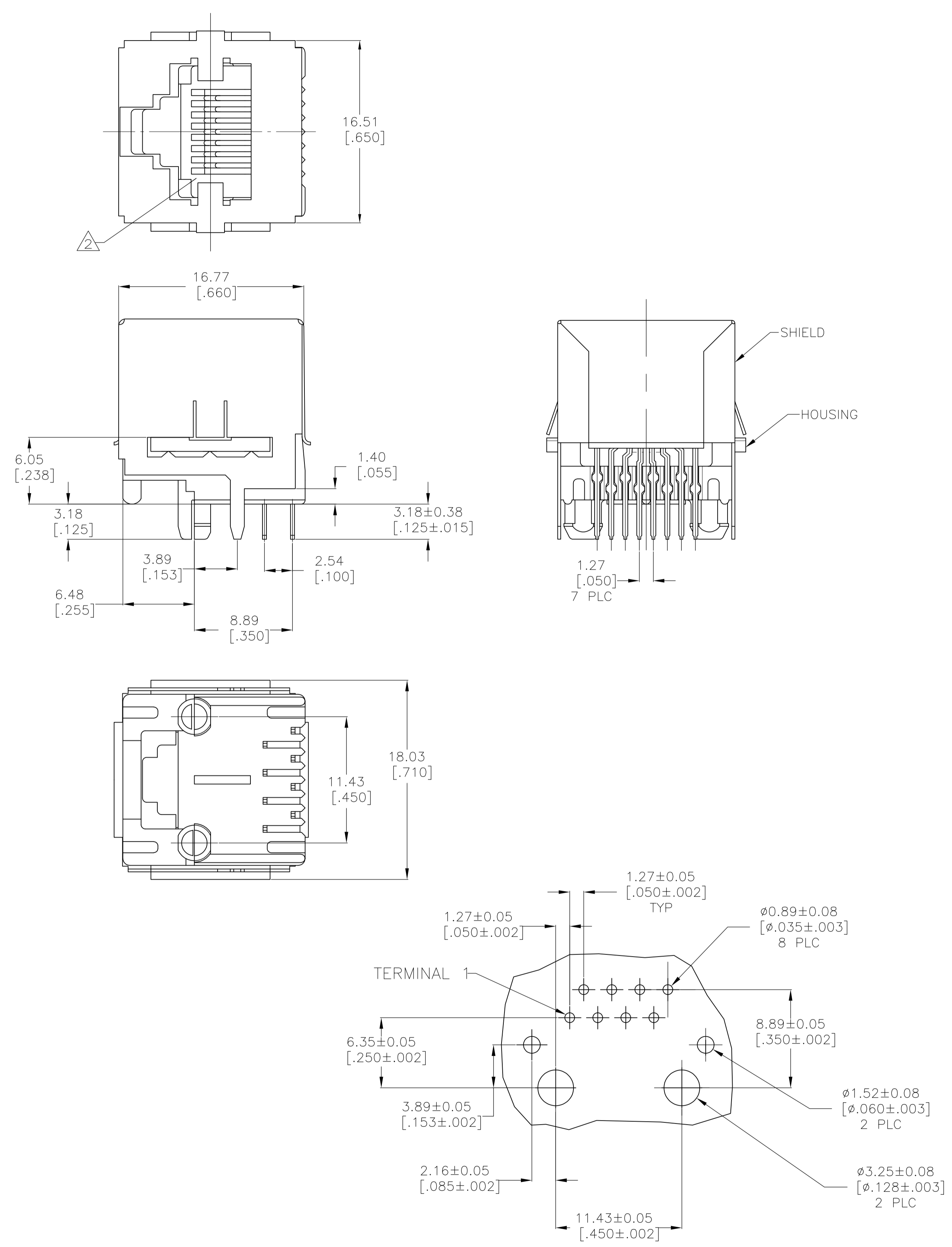


- MATERIAL:  
 HOUSING - POLYESTER MOLDING COMPOUND, UL 94-VO, COLOR: BLACK  
 TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 $\mu$ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 $\mu$ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 $\mu$ m[.000050] MIN THICK NICKEL UNDERPLATE  
 SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0 $\mu$ m[.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

3. BULK PACKAGED IN A TRAY



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

RECOMMENDED PANEL CUTOUT

5557484-1  
PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	G. ATTADIA - 10JUN2005	TE Connectivity
DIMENSIONS: mm [INCHES]		CHK	J. WESTMAN 10JUN2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER 10JUN2005	NAME
0 PLC ± -		PRODUCT SPEC		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS
1 PLC ± -		APPLICATION SPEC		108-1163
2 PLC ± -		SIZE		114-2048
3 PLC ± 0.13[0.005]		WEIGHT		A1 00779
4 PLC ± -		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV D1